

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	APPLICATION NUMBER 10/908814
NATURE OF CONVEYANCE:	ASSIGNMENT OF ASSIGNOR'S INTEREST	

CONVEYING PARTY DATA

Name	Execution Date
Ching-Wen Teng	2005-05-24
Ming-Hsing Kao	2005-05-24
Chin-Kun Lin	2005-05-24
Er-Yang Chua	2005-05-24
Lee-Lee Lau	2005-05-24

RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
UNITED MICROELECTRONICS CORP.	No.3, Li-Hsin Road 2, Science-Based Industrial Park		Hsin-Chu City	TAIWAN	

CORRESPONDENCE DATA

FAX NUMBER: 8064986673

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 027765

NAME OF PERSON SIGNING:	WINSTON HSU
DATE SIGNED:	2005-05-25

Total Attachments: 3

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CH \$40.00 503105 10908814

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Ching-Wen Teng Nationality: R.O.C.

Address: No. 15, Lane 282, Puhsin-Wunhua St., Yangmei Town, Tao-Yuan Hsien, Taiwan, R.O.C.

Name: Ming-Hsing Kao Nationality: R.O.C.

Address: No. 220, Chingcheng Rd., Taitung City, Tai-Tung Hsien, Taiwan, R.O.C.

Name: Chin-Kun Lin Nationality: R.O.C.

Address: No. 112, Ching-Yun St., San-Ming Dist., Kao-Hsiung City, Taiwan, R.O.C.

Name: Er-Yang Chua Nationality: Singapore

Address: Blk 104 Jalan Rajah #10-61, Singapore

Name: Lee-Lee Lau Nationality: Malaysia

Address: No.107, Lot26, 6 1/2, Air Keroh Village, Melaka, Malaysia

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"CMP Method and Device Capable of Avoiding Slurry Residues"

Which is found in :

- (a) 1 U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAY 24 2005 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Ching-Wen Teng

陳清文 Teng ching wen

Ming-Hsing Kao

高鳴興 Kao Ming Hsing

Chin-Kun Lin

林欽坤 Lin chin kun

Er-Yang Chua

蔡爾揚 CHUA ER-YANG

Lee-Lee Lau

劉麗潔 Lee-Lee Lau